

#### **SPECIFICATIONS**

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MASS PRODUCTION CODE : PH128160T-066-L03Q

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# **Customer Approved**

Date:

POWERTIP
2015.09.01

JS RD APPROVED

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- Preliminary specification for design input
- Specification for sample approval

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# **History of Version**

Date	Ver.	Edi.	Description	Page	Design by
03/11/2011	01	001	New Drawing	4	Violin Huang
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04/07/2014	01	003	Modify Viewing Angle Show Application Notes & Refer Initial Code	6 11~14	劉進
08/24/2015	01	004	Show Backlight Life Time	8	劉進
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Total: 27 Pages



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#### 1. SPECIFICATIONS

#### 1.1 Features

#### **Main LCD Panel**

Item	Standard Value		
Display Type	128 * (R · G · B) * 160 Dots		
LCD Type	a-Si TFT, Normally White TN mode, Transmissive		
Screen size(inch)	1.77 (Diagonal)		
Viewing Direction	12 O'clock		
Color configuration	R.G.B. vertical stripe		
Interface	8-bit interface for 80 system		
Other(controller / driver	OTZZOED( O a. a.d. OEK O)		
IC)	ST7735R( Support 65K Colors )		
	THIS PRODUCT CONFORMS THE ROHS OF PTC		
ROHS	Detail information please refer web site:		
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/		

# 1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	34.0 (W) * 47.0 (L) * 2.4 (H)(MAX)	mm

#### **TFT LCD Panel**

Item	Standard Value		
Viewing Area (LCD)	29.032 (W) * 36.04 (L)	mm	
Active Area (LCD)	28.032 (W) * 35.04 (L)	mm	

Note: For detailed information please refer to LCM drawing.



# 1.3 Absolute Maximum Ratings

#### Module

Item	Symbol	Condition	Min.	Max.	Unit
System Dower Supply Voltage	VDD	•	-0.3	+4.6	V
System Power Supply Voltage	VGH-VGL	-	-0.3	30.0	V
Input Voltage	VIN	-	-0.3	VDD+0.3	V
Operating Temperature	T <sub>OP</sub>	-	-20	+70	°C
Storage Temperature	T <sub>ST</sub>	-	-30	+80	°C
Storage Humidity	H <sub>D</sub>	Ta ≦ 60 °C	20	90	%RH

# 1.4 DC Electrical Characteristics

GND = 0V, Ta = 25°C Module

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Interface operation voltage	VDD	I/O supply voltage		2.8	-	V
Input High Voltage	ViH		0.7*VDD	-	VDD	V
Input Low Voltage	VıL	·	GND	-	0.3*VDD	V
Output High Voltage	Vон	IOH=-0.1mA	0.8*VDD	-	VDD	V
Output Low Voltage	Vol	IOL=0.1mA	GND	-	0.2*VDD	V
Supply Current	IDD	VDD= 2.8V	-	1.0	1.5	mA



#### 1.5 Optical Characteristics

#### **TFT LCD Panel**

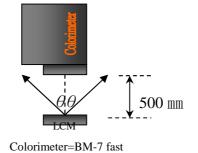
VDD = 2.8V, Ta=25°C

Item	Item		Condition	Min.	Тур.	Max.	unit	
Response tin	Response time		-	-	30	45	ms	Note2
	Тор	θΥ+		-	45	-		
Viowing angle	Bottom	θΥ-	CR ≥ 10	-	15	-	Dog	Noto 4
Viewing angle	Left	θX-	CR 2 10	-	45	-	Deg.	Note4
	Right	θΧ+		-	45	-		
Contrast rati	0	CR		150	200	-	,	Note3
	White	Х		0.23	0.28	0.33		
	vviile	Υ		0.26	0.31	0.36		
	Dod	Х		0.58	0.63	0.68		
Color of CIE Coordinate	Red	Υ	IF= 30mA	0.29	0.34	0.39		Note1
(With B/L)	Croon	Х		0.28	0.33	0.38	_	NOLET
,	Green	Y		0.56	0.61	0.66		
	Dlue	Х		0.07	0.14	0.19		
	Blue	Υ		0.03	0.08	0.13		
Average Bright	ness							
Pattern=white display		IV	IF= 30mA	230	290	-	cd/m <sup>2</sup>	Note1
(With B/L)								

#### Note1:

- 1 :  $\triangle B = B(min) / B(max) \times 100\%$ .
- 2 : Measurement Condition for Optical Characteristics:
  - a: Environment: 25°C±5°C / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance:  $500 \pm 50$  mm,  $(\theta = 0^{\circ})$ .
  - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%.



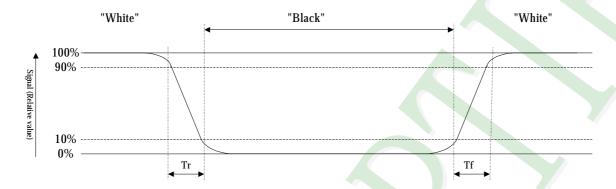




#### Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

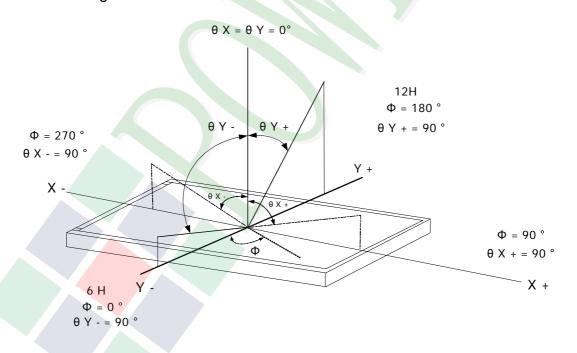
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





# 1.6 Backlight Characteristics

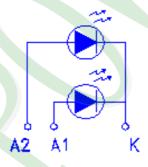
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°ℂ	-	60	mA
Reverse Voltage	VR	Ta =25°ℂ	-	5.0	V
Power Dissipation	PD	Ta =25°ℂ	-	180	mW

**Electrical / Optical Characteristics** 

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=30mA	-	3.3	3.5	V
Average Brightness (without LCD)	IV	IF=30mA	3200	3500	/-	cd/m <sup>2</sup>
Color of CIE Coordinate	X	IF=30IIIA	0.25	0.28	0.31	
(without LCD)	Y		0.25	0.28	0.31	_
Color	4		White			

# Internal Circuit Diagram



Other Description

Item	Conditions	Description
Life Time	Ta =25°ℂ	30000 hrs
Life Time	IF= 20mA	30000 1115



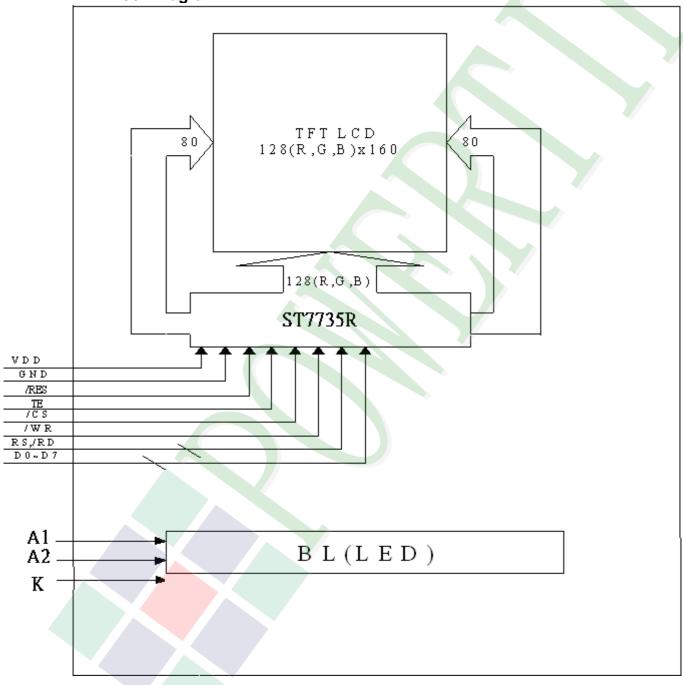
### 2. MODULE STRUCTURE

# 2.1 Counter Drawing

### 2.1.1 LCM Mechanical Diagram

\* See Appendix

### 2.1.2 Block Diagram



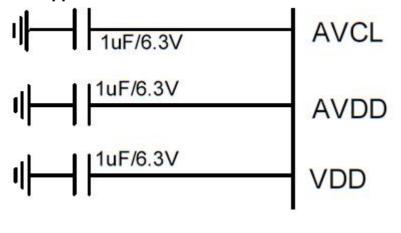


# 2.2 Interface Pin Description

Pin No.	Symbol	Function
1	K	Power Supply for LED Backlight Cathode input.
2	A2	Power Supply for LED Backlight Anode input.
3	A1	Power Supply for LED Backlight Anode input.
4	RD	Read signal input , Active "L".
5	RS	The signal for command or parameter select under parallel mode Low: command.; High: parameter.
6	D1	Bi-directional data bus.
7	D3	Bi-directional data bus.
8	D5	Bi-directional data bus.
9	D7	Bi-directional data bus.
10	TE	Tearing effect output pin to synchronies MPU to frame rate,activated by S/W command
11	RESET	This signal will reset the device and it must be applied to properly initialize the chip, Active "L".
12	CS	Chip selection pin, Active "L".
13	D6	Bi-directional data bus.
14	D4	Bi-directional data bus.
15	D2	Bi-directional data bus.
16	D0	Bi-directional data bus.
17	WR	Write enable in MPU parallel interface, Active "L".
18	GND	System ground
19	VDD	Power supply for analog, digital , I/O system and booster circuit  Connect to Capacitor: VDD GND 6.3V 1.0 uF
20	AVDD	Power pin for analog circuits.  Connect to Capacitor: AVDD   GND 6.3V 1.0 uF
21	AVCL	A power supply pin for generating GVCL.  Connect to Capacitor: AVCL   GND 6.3V 1.0 uF
22	GND	System ground



# 2.2.1 Application Notes





```
2.2.2 Refer Initial code
void Initial DISPLAY CONTROL(void)
{
       WriteCOM_CN(0x11);
       delay(20);
       WriteCOM_CN(0xf0);
       WriteDAT1_MAIN(0x01);
       WriteCOM_CN(0xf6);
       WriteDAT1_MAIN(0x00);
       WriteCOM_CN(0xB1);
       WriteDAT1 MAIN(0x01);
       WriteDAT1_MAIN(0x2c);
       WriteDAT1_MAIN(0x2d);
       WriteCOM_CN(0xB2);
       WriteDAT1_MAIN(0x01);
       WriteDAT1_MAIN(0x2c);
       WriteDAT1_MAIN(0x2b);
       WriteCOM_CN(0xb3);
       WriteDAT1_MAIN(0x01);
       WriteDAT1_MAIN(0x2c);
       WriteDAT1 MAIN(0x2b);
       WriteDAT1 MAIN(0x01);
       WriteDAT1_MAIN(0x2c);
       WriteDAT1 MAIN(0x2b);
       WriteCOM_CN(0xb4);
       WriteDAT1 MAIN(0x07);
       WriteCOM_CN(0xb6);
       WriteDAT1_MAIN(0x84);
       WriteDAT1 MAIN(0xf0):
       WriteDAT1 MAIN(0x20);
       WriteCOM_CN(0xC0);
       WriteDAT1 MAIN(0xa2);
       WriteDAT1_MAIN(0x02);
       WriteDAT1_MAIN(0x04);
       WriteCOM_CN(0xc1);
       WriteDAT1_MAIN(0xc5);
```

WriteCOM\_CN(0xc2); WriteDAT1\_MAIN(0x0a); WriteDAT1 MAIN(0x00);



WriteCOM\_CN(0xc3); WriteDAT1\_MAIN(0x8a); WriteDAT1 MAIN(0x2a); WriteCOM\_CN(0xc4); WriteDAT1\_MAIN(0x8a); WriteDAT1 MAIN(0xee): WriteCOM\_CN(0xc5); WriteDAT1\_MAIN(0x04); WriteCOM\_CN(0x36); WriteDAT1\_MAIN(0xc8); WriteCOM\_CN(0xe0); WriteDAT1 MAIN(0x0f); WriteDAT1\_MAIN(0x1a); WriteDAT1 MAIN(0x0f); WriteDAT1\_MAIN(0x18); WriteDAT1\_MAIN(0x2f); WriteDAT1 MAIN(0x28); WriteDAT1 MAIN(0x20); WriteDAT1 MAIN(0x22); WriteDAT1\_MAIN(0x1f); WriteDAT1 MAIN(0x1b); WriteDAT1 MAIN(0x23); WriteDAT1\_MAIN(0x37); WriteDAT1\_MAIN(0x00); WriteDAT1 MAIN(0x07); WriteDAT1 MAIN(0x02); WriteDAT1 MAIN(0x10); WriteCOM CN(0xe1); WriteDAT1 MAIN(0x0f); WriteDAT1\_MAIN(0x1b); WriteDAT1\_MAIN(0x0f); WriteDAT1\_MAIN(0x17); WriteDAT1 MAIN(0x33); WriteDAT1\_MAIN(0x2c); WriteDAT1\_MAIN(0x29); WriteDAT1 MAIN(0x2e); WriteDAT1 MAIN(0x30); WriteDAT1 MAIN(0x30); WriteDAT1\_MAIN(0x39); WriteDAT1\_MAIN(0x3f); WriteDAT1 MAIN(0x00); WriteDAT1\_MAIN(0x07); WriteDAT1\_MAIN(0x03); WriteDAT1\_MAIN(0x10);

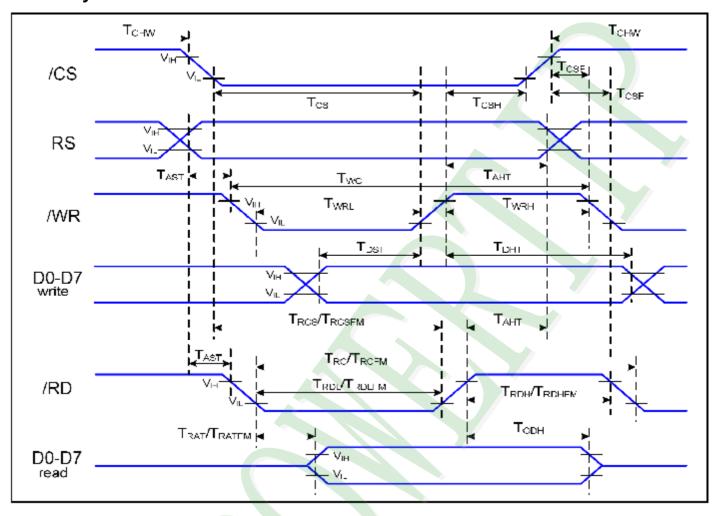


WriteCOM\_CN(0x29);





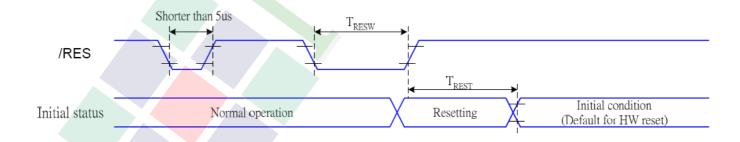
# 2.3 Timing Characteristics 80-System Bus Interface





Signal	Symbol	Parameter	Min	Max	Unit	Description
RS ·	TAST	Address setup time	10		ns	
Ko .	TAHT	Address hold time (Write/Read)	10		ns	
	TCHW	Chip select "H" pulse width	0		ns	
	TCS	Chip select setup time (Write)	<b>1</b> 5		ns	
/cs	TRCS	Chip select setup time (Read ID)	45		ns	
/63	TRCSFM	Chip select setup time (Read FM)	350		ns	
	TCSF	Chip select wait time (Write/Read)	10		ns	
	TCSH	Chip select hold time	10		ns	
	TWC	Write cycle	100		ns	
/WR	TWRH	Control pulse "H" duration	30		ns	
	TWRL	Control pulse "L" duration	30		ns	
	TRC	Read cycle (ID)	160		ns	
/RD (ID)	TRDH	Control pulse "H" duration (ID)	90		ns	When read ID data
	TRDL	Control pulse "L" duration (ID)	45		ns	
/RD	TRCFM	Read cycle (FM)	450		ns	When read from frame
(FM)	TRDHFM	Control pulse "H" duration (FM)	150		ns	memory
(1 141)	TRDLFM	Control pulse "L" duration (FM)	150		ns	momory
	TDST	Data setup time	10		ns	
	TDHT	Data hold time	10		ns	
D0-D7	TRAT	Read access time (ID)		40	ns	For CL=30pF
	TRATEM	Read access time (FM)		40	ns	
	TODH	Output disable time		80	ns	

# Reset Timing

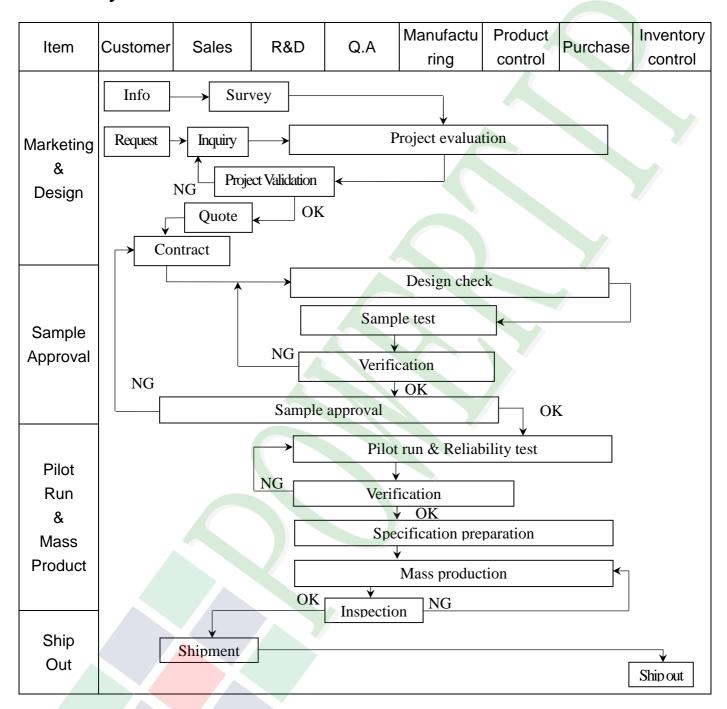


Related Pins	Symbol	Parameter	MIN	MAX	Unit
	tRESW	Reset pulse duration	10	-	us
/RES	tREST	Reset cancel	-	5	ms
	IKEST			120	ms

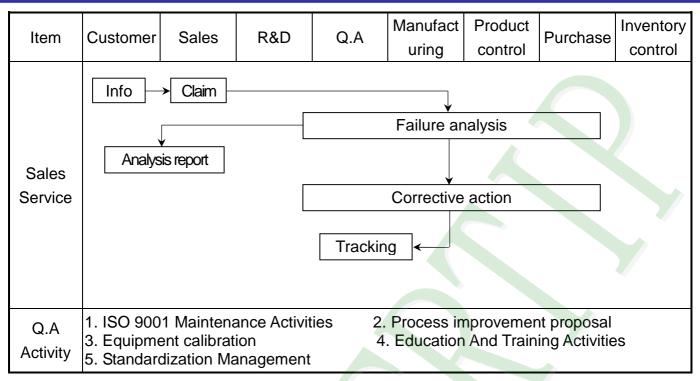


### 3. QUALITY ASSURANCE SYSTEM

### 3.1 Quality Assurance Flow Chart



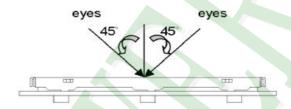




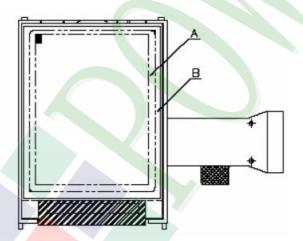


# 3.2. Inspection Specification

- ◆Scope : The document shall be applied to TFT-LCD Module for less than 3, 5" (Ver.B01).
- ◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment: Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level: Major Defect AQL: 0,4; Minor Defect AQL: 1,5
- **♦**OUT Going Defect Level: Sampling.
- ◆Standard of the product appearance test:
  - a. Manner of appearance test:
  - (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
  - (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

B area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)



# igspace Specification For TFT-LCD Module Less Than 3.5":

NO	Item			Criteri	ion	Level	
		1. 1The part number is inconsistent with work order of production.			Major		
01	Product condition	1. 2 Mixed product types.					
		1. 3 As	sembled	in inverse direction		Major	
02	Quantity	2. 1Th	e quantit	y is inconsistent wit	h work order of production.	Major	
03	Outline dimension		3. 1 Product dimension and structure must conform to structure diagram.				
		4. 1 Mi	issing lin	e character and ico	n.	Major	
		4. 2 No function or no display.				Major	
04	Electrical Testing	4. 3 Display malfunction.			Major		
		4. 4 LCD viewing angle defect.			Major		
		4. 5 Cu	irrent co	nsumption exceeds	product specifications.	Major	
				Item	Acceptance (Q'ty)		
	Dot defect			Bright Dot	≦ 2		
			Dot	Dark Dot	≦ 3		
0.5	(Bright dot \		Defect	Joint Dot	≦ 2		
05	Dark dot)			Total	≦ 3	Minor	
		5. 1 In	spection	pattern : full white	, full black , Red , Green and		
	On -display	blue screens.					
		5. 2 It	is defined	l as dot defect if def	Sect area $> 1/2$ dot.		
		5. 3 Th	e distanc	e between two dot	defect ≧5 mm.		



### igspace Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion					
		6. 1 Round type ( Non-display or display) :					
		Dimension	Acceptance				
	DI 1 114	(diameter∶Φ)	A area	B area			
	Black or white dot \ scratch \	$\Phi \le 0.15$	Ignore				
	contamination	$0.15 < \Phi \leq 0.20$	2				
	Round type	$0.20 < \Phi \leq 0.30$	2	Ignore			
	→ <u>x</u> <u> </u> <u> </u>	$\Phi > 0.30$	0				
06	Y Y	Total	3		Minor		
	$\Phi = (x+y)/2$	6. 2 Line type( Non-display or display) :					
	Line type	Dimension	Acceptar	Acceptance (Q'ty)			
	↓	Length (L) Width (W)	A area	B area			
	~ ↑ W	$$ $W \leq 0.0$	1gnore				
	→ L I←	$L \le 5.0$ 0.03 $< W \le 0.03$	5 3				
		W >0.0	As round type	Ignore			
		Total	3				
		Dimension (diameter : Φ)	Acceptance (				
			A area	B area			
07	Polarizer	Φ ≤ 0.20	Ignore		Minor		
01	Bubble	$0.20 < \Phi \leq 0.50$	3	Ignore	WILLION		
		$\Phi > 0.50$	0	25			
		Total	3				



# igspace Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion		Level
		Z : The thickness of crack V	Y : The width of crack. V : terminal length a : LCD side length	
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	nck between panels:	
		Y Z	Z Y	
08	The crack of glass	SP Y [OK]	SP [NG]	Minor
		Seal width	Y	
		X Y	z	
		≦ a Crack can't enter viewing area	≦1/2 t	
		≤ a Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	
4				



### ◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion	Level					
		Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  8. 1. 2 Corner crack:  X: The width of crack. W: terminal length a: LCD side length						
		$\begin{array}{ c c c c c }\hline X & Y & Z \\ & \leq 1/5 \ a & \begin{array}{ c c c c }\hline Crack can't enter & Z & \leq 1/2 \ t \\ & viewing area & \end{array}$						
08	The crack of glass	≤1/5 a Crack can't exceed the half of SP width. 1/2 t < Z ≤ 2 t	Minor					
,,,,,	<b>s</b>	8.2 Protrusion over terminal:						
		8. 2. 1 Chip on electrode pad:  W  X  X  W  X  X  X  X  X  X  X  X  X						
		X Y Z						
		Front $\leq$ a $\leq$ 1/2 W $\leq$ t						
		Back $\leq$ a $\leq$ W $\leq$ 1/2 t						



### ◆Specification For TFT-LCD Module Less Than 3.5":

X: The length of crack Y: The width of crack. Z: The thickness of crack W: terminal length t: The thickness of glass a: LCD side length	NO
8. 2. 2 Non-conductive portion:    W	



# $\spadesuit$ Specification For TFT-LCD Module Less Than 3. 5" :

NO	Item	Criterion	Level
	Backlight elements	9. 1 Backlight can't work normally.	Major
09		9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
	diagram.  10. 2 No short circuits in components on PCB or FPC.  10. 3 Parts on PCB or FPC must be the same as on the production	10. 1 Pin type · quantity · dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC.	Major
10		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10	appearance	10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10, 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC ) is ≤1.5 mm.	Minor



# 4. RELIABILITY TEST

#### **Reliability Test Condition** 4.1

NO.	TEST ITEM	TEST C	ONDITION			
1	High Temperature Storage Test	Keep in +80°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
2	Low Temperature Storage Test	Keep in -30°C 96 hrs Surrounding temperature, ther 4hrs.	storage at normal condition			
3	High Temperature / High Humidity Storage Test	Keep in +60 / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)				
4	Temperature Cycling Storage Test	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$				
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-  1. Temperature ambiance: 15 2. Humidity relative: 30%~60 3. Energy Storage Capacitance 4. Discharge Resistance(Rd): 5. Discharge, mode of operati	% e(Cs+Cd) : 150pF±10% 330Ω±10%			
		1 sec) (Tolerance if the	n successive discharges at least output voltage indication : ±5%)			
6	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequency (1 min/sweep)</li> <li>The amplitude of vibration :1.5 mm</li> <li>Each direction (X \ Y \ Z) duration for 2 Hrs</li> </ol>				
7	Drop T <mark>est</mark> (Packaged)	Packing Weight (Kg) Drop Height (cm)  0 ~ 45.4 122  45.4 ~ 90.8 76  90.8 ~ 454 61  Over 454 46				
		Drop Direction : 1 corner / 3 edges / 6 sides each 1 time				



#### 5. PRECAUTION RELATING PRODUCT HANDLING

#### 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- If the liquid crystal touches your skin or clothes, please wash it off immediately by 5.1.2 using soap and water.

#### **5.2 HANDLING**

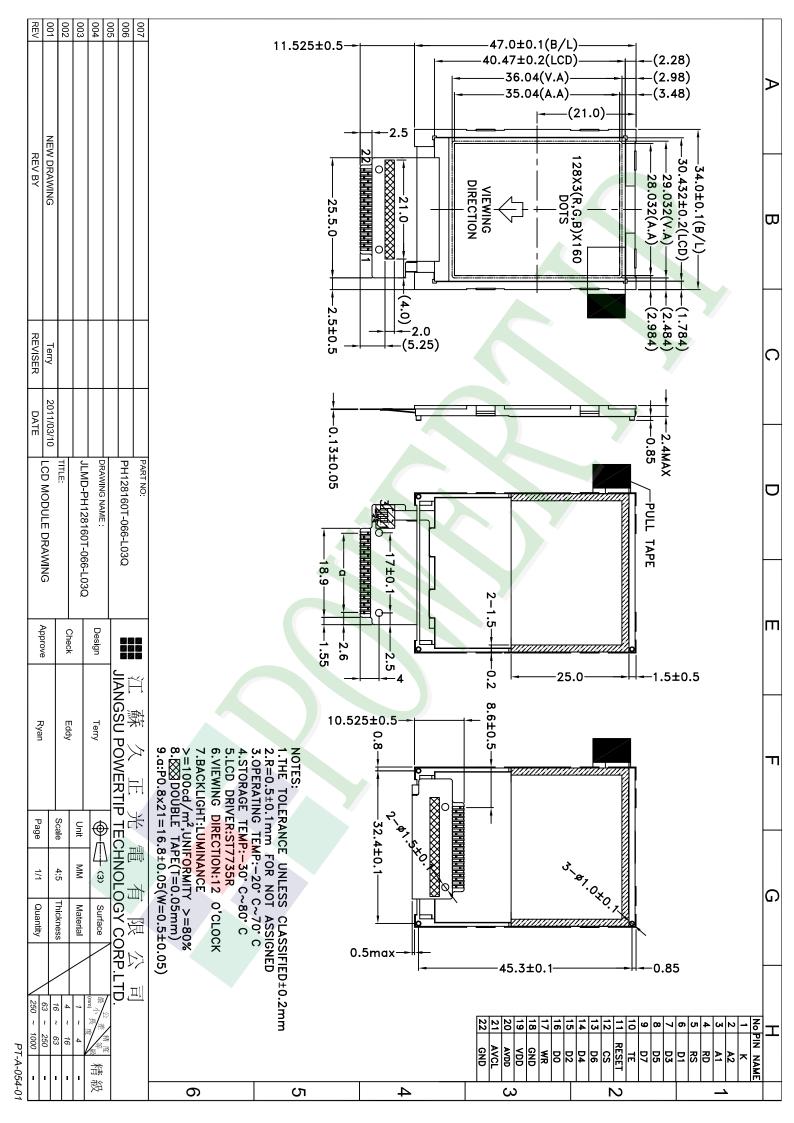
- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- Do not remove the panel or frame from the module. 5.2.3
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- Do not touch the display area with bare hands, this will stain the display area. 5.2.6
- Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a 5.2.7 cleaning naphtha solvent.
- To control temperature and time of soldering is 320 ± 10°C and 3-5 sec. 5.2.8
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

#### **5.3 STORAGE**

- Store the panel or module in a dark place where the temperature is 25°C ± 5°C 5.3.1 and the humidity is below 65% RH.
- Do not place the module near organics solvents or corrosive gases. 5.3.2
- Do not crush, shake, or jolt the module. 5.3.3

#### 5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period
  - The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- Unaccepted responsibility 5.4.2
  - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



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Doc	uments NO. JPKG-PH128160T-066-		ng Specification	ns Ryan	Eddy	Terry			
	(For Tray)								
	L裝材料規格表 (Packaging M			<u> </u>	Γ				
No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight			
1	成品 (LCM)	PH128160T-066-L03Q	34.0 X 47.0	0.0054	864	4.6656			
2	多層薄膜(1)POF	OTFILM0BA03ABA	19"X350X0.015		6				
3	TRAY 盤 (2)Tray	TYPH12816044BH	352 X 260 X 10.8	0.1	60	6.0			
4	内盒(3)Product Box	BX36627063ABBA	393 X 274 X 68	0.2692	6	1.6152			
5	保利龍板(4)Polylon board	OTPLB00PL08ABA	550 X 393 X 20	0.0284	2	0.0568			
6	外紙箱(5)Carton	BX57041027CCBA	570 X 410 X 265	1.4208	7	1.4208			
7	舒美墊(7)	OTFOAMPHD05ABA	310 X 225 X 1	0.0005	54	0.027			
8									
9	####################################	10.50 17.14	O CT The Latel of the						
	整箱總重量 (Total LCD Weight 箱數量規格表 (Packaging Specifi		0% 取小數2位						
	CM quantity per box: no per tray	16	x no of tray	9	= 144				
(2)T	otal LCM quantity in carton: quant	tity per box 144	x no of boxes	6	= 864				
Use empty tray 空									
MODE LOT	NO: YTITY:	特記事巧	Detail B Tray 2 Tray 1	3.可適用於單 It's also suita					

2.TRAY盤相疊時,需旋轉180度,請詳見B視圖 Rotate tray 180 degrees and place on top of stack.

Check the tray stack using Fig. B.